

ABSTRACT

A semiconductor device includes an insulating substrate 2 having an obverse surface formed with a die pad 3, a rectangular semiconductor chip 7 such as an LED chip bonded to the die pad with a die bonding material 10, and a molded portion 9 made of a synthetic resin for packaging the semiconductor chip. The die pad 3 may be rectangular with dimensions close to those of the semiconductor chip or circular with a diameter close to the diagonal dimension of the semiconductor chip, whereby the positioning and orienting of the semiconductor chip can be accurately performed in bonding the semiconductor chip.